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NOTICE TO MAXIM/DALLAS CUSTOMERS

RoHS and Material Declaration Certificate

RoHS COMPLIANCE:

- Lead free integrated circuits supplied by Dallas Semiconductor/Maxim Integrated Products comply with the EU RoHS Directive 2002/95/EC and WEEE Directive 2002/960/EC.
- Lead free integrated circuits do not contain lead (Pb), cadmium (Cd), mercury (Hg), hexavalent chromium (Cr), Polybrominated Biphenyls (PBBs) or Polybrominated Diphenyl Ethers (PBDEs), and are therefore considered RoHS compliant.
- Lead free solder finishes used by Dallas Semiconductor/Maxim Integrated Products consist of 100% matte tin.
- Some products (e.g. wafer level and flip chip packages) are assembled with high lead solders (>85% lead) and some are assembled with quartz crystals (piezoelectric devices) containing lead, but qualify for a RoHS exemption under Article 4, section 7 of the EU Directive 2002/95/EC.

SUBSTANCES OF CONCERN:

- Dallas and Maxim products do not contain chlorinated organic compounds, brominated organic compounds (e.g. PBBs or PBDEs), organic tin compounds, asbestos, AZO compounds, formaldehyde, ozone depleters, residual monomers, benzene or poly vinyl chloride (except shipping tubes).

SUBSTANCES USED TO MANUFACTURE DALLAS/MAXIM LEAD FREE PRODUCTS:

Component	Substance	CAS#
Lead frame	Copper (Cu)	7440-50-8
Lead frame	Iron (Fe)	7439-89-6
Lead frame	Zinc (Zn)	7440-66-6
Lead frame	Magnesium (Mg)	7439-95-4
Lead frame	Nickel (Ni)	7400-02-0
Lead frame	Chromium (Cr)	7440-47-3
Molding Compound	Antimony (Sb ₂ O ₃)	1309-64-4
Molding Compound	Bromine (Br)	10097-32-2
Molding Compound	Silica (SiO ₂)	14808-60-7
Molding Compound	Resin	N/A
Die Attach Epoxy	Silver Filler (Ag)	7440-22-4
Die Attach Epoxy	Epoxy	N/A
Bond Wire	Gold (Au)	7440-57-5
Surface Finish	Tin (Sn)	7440-31-5
Silicon Chip	Silicon	7440-21-3

MAXIM INTEGRATED PRODUCTS, INC.

Alan P. Hale, Vice President

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